

AF/1763

Amendment

TOWNSEND and TOWNSEND and CREW LLP
(415) 576-0200

Corres. and Mail

Attorney Docket No. A1126/T08910
PTC Ref No. 016301-008910US



BOX AF

In re application of: KRAMADHARI V. RAVI et al.

Date: December 15, 2000

Application No.: 09/362,504

I hereby certify that this is being deposited with the United States Postal Service as first class mail in an envelope addressed to:

Filed: July 27, 1999

Assistant Commissioner for Patents
Washington, D.C. 20231

Group Art Unit: 1763

For: METHOD FOR REDUCING THE INTRINSIC STRESS
OF HIGH DENSITY PLASMA FILMS

THE ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Signed:

RESPONSE TO OFFICE ACTION UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE-EXAMINING GROUP 1763

Sir:

Transmitted herewith is an amendment in the above-identified application.

If any extension of time is needed, then this response should be considered a petition therefor.

The filing fee has been calculated as shown below:

(Col. 1)	(Col. 2)	(Col. 3)		
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA
TOTAL	* 21	MINUS	** 21	= 0
INDEP.	* 5	MINUS	*** 5	= 0
[] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM				

SMALL ENTITY		OR	OTHER THAN SMALL ENTITY	
RATE	ADDIT. FEE		RATE	ADDIT. FEE
x \$9.00 =			x \$18.00 =	\$0.00
x \$40.00 =			x \$80.00 =	\$0.00
+ \$135.00 =			+ \$270.00 =	
TOTAL ADDIT. FEE		OR	TOTAL	\$0.00

[X] No fee is due.

Please charge Deposit Account No. 20-1430 as follows:

[] Claims fee

[X] Any additional fees associated with this paper or during the pendency of this application

NO extra copies of this sheet are enclosed.

PLEASE ADDRESS ALL CORRESPONDENCE TO:

PATENT COUNSEL

APPLIED MATERIALS, INC.

P.O. BOX 450A

SANTA CLARA, CA 95052

TOWNSEND and TOWNSEND and CREW LLP

Chun-Pok Leung
Reg. No. 41,405
Attorneys for Applicant

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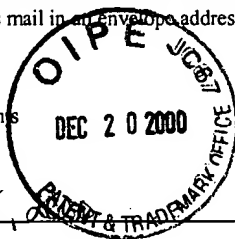
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Assistant Commissioner for Patents
Washington, D.C. 20231

On

December 15, 2000



TOWNSEND and TOWNSEND and CREW LLP

By:

RESPONSE TO OFFICE ACTION
UNDER 37 CFR 1.116 EXPEDITED
PROCEDURE - EXAMINING GROUP
1763

PATENT

Attorney Docket No.: A1126/T08910
TTC Reference No.: 16301-008910

#14 E ME
12/26/00
MM

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

KRAMADHATI V. RAVI et al.

Application No.: 09/362,504

Filed: July 27, 1999

For: METHOD FOR REDUCING THE
INTRINSIC STRESS OF HIGH
DENSITY PLASMA FILMS

Examiner: Rudy Zervigon

RESPONSE TO OFFICE ACTION UNDER
37 CFR 1.116 EXPEDITED PROCEDURE
EXAMINING GROUP 1763

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Box AF

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Final Office Action mailed October 27, 2000, please
reconsider this application in view of the following comments.

IN THE CLAIMS:

The claims are unamended, but are reproduced below for the Examiner's
convenience and reference.

16. An integrated circuit formed on a semiconductor substrate by the
method of:

- a) flowing a process gas into a substrate processing chamber;